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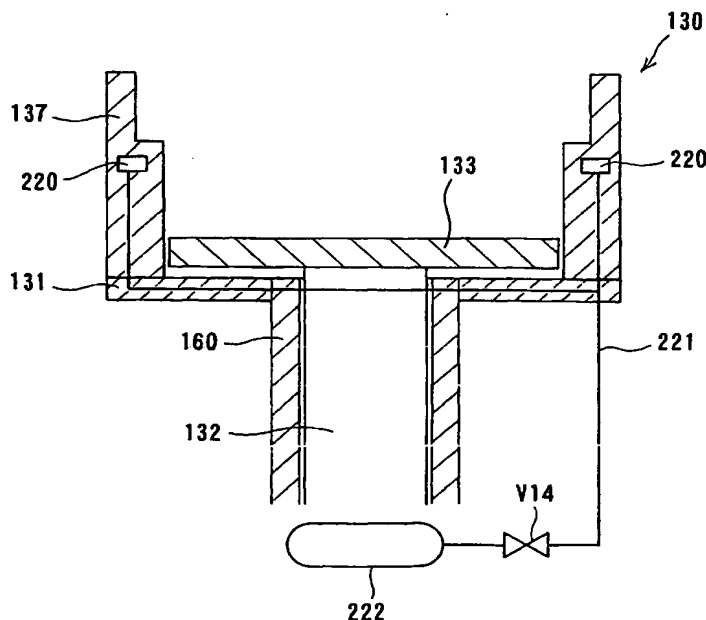
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(54) Title: POLISHING APPARATUS



(57) Abstract: A polishing apparatus has a top ring (1) configured to hold a semiconductor wafer (W) on a substrate holding surface and a pusher (130) configured to deliver the semiconductor wafer (W) to the top ring (1) and receive the semiconductor wafer (W) from the top ring (1). The pusher (130) includes a push stage (133) having a substrate placement surface on which the semiconductor wafer (W) is placed and an air cylinder (135) configured to vertically move the push stage (133). The pusher (130) also includes a high-pressure fluid port (220) configured to eject a high-pressure fluid toward the semiconductor wafer (W).

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